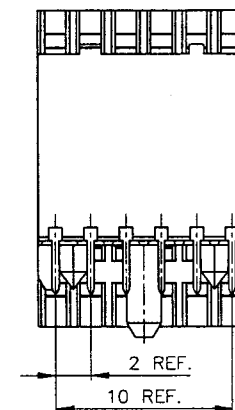
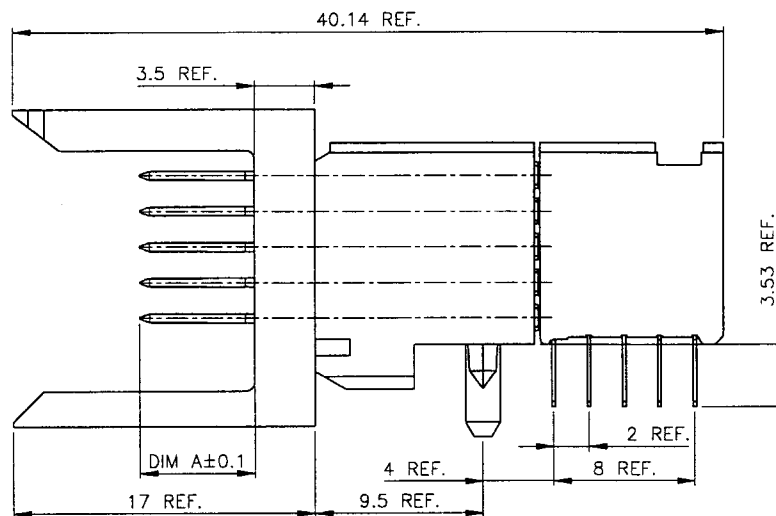
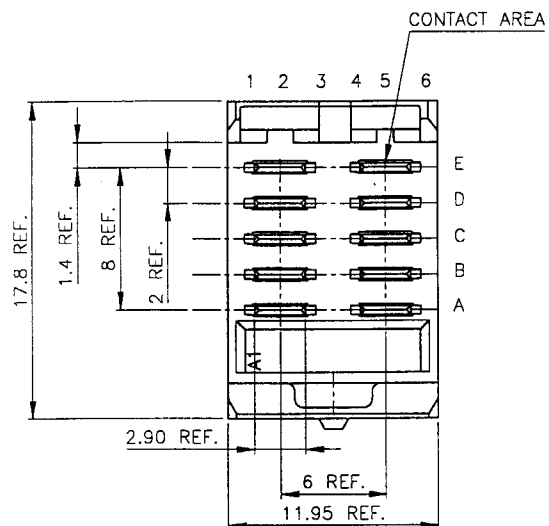
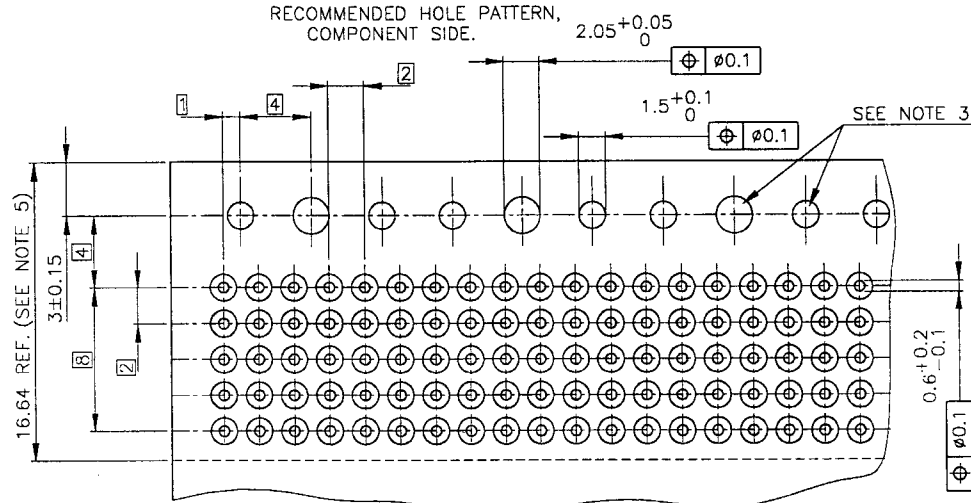


PRODUCT NUMBER:	PCB THICKNESS	DIM A SEE DRAWING	REMARKS
85938-X02	2.4	89099-X11	HEAT STAKE PEG
85938-X12	2.4	89099-X11	PRESS PEG (NOT SHOWN)
85938-X13	2.4	89099-X12	PRESS PEG (NOT SHOWN)
85938-X14	2.4	89099-X10	PRESS PEG (NOT SHOWN)

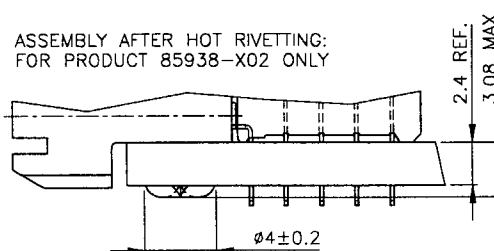
PLATING IN CONTACT AREA		
PLATING CODE	THICKNESS	UNDERPLATING
-1YZ	0.8 μ m GOLD	1.3 μ m Ni min.
-2YZ	2.0 μ m GOLD	1.3 μ m Ni min.
-3YZ	1.3 μ m GOLD	1.3 μ m Ni min.
-9YZ	0.8 μ m GXT	1.3 μ m Ni min.



RECOMMENDED HOLE PATTERN,
COMPONENT SIDE.



ASSEMBLY AFTER HOT RIVETTING:
FOR PRODUCT 85938-X02 ONLY



- NOTES:
- BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS
FLAME RETARDANT ACC. UL 94-V0
 - PIN MATERIAL: PHOSPHOR BRONZE.
 - INDICATED HOLES ARE UNPLATED.
 - PLATING OF COMPLIANT SECTIONS 0.5-1.5 μ m SnPb 85-97
 - SET BACK FOR PRESS BLOCK

mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY		BERG ELECTRONICS	
lit.	ecr. no.	dr.	date	linear	projection	hite	R/A HEADER SPECIAL POWER
A	H50485	RVI	950822				
B	H50618	RVI	951019				
C	H80638	QDB	961010	angles			
D	H70527	QDB	970819	dr.	R VISSCHERS	950822	product family METRAL (tm) code 213
E	H80709	QDB	981022	engr.	P. SCHALK	950822	size dwg no. A2 85938 sheet 1 of 1
				ch.	P. SCHALK	950822	
				add.	P. SCHALK	950822	
sheet index	revision	sheet	1				